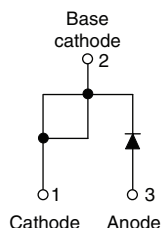


HEXFRED®

Ultrafast Soft Recovery Diode, 8 A



TO-220AC

FEATURES

- Ultrafast recovery
- Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- Specified at operating conditions
- Designed and qualified for industrial level

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

HFA08TB60 is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A continuous current, the HFA08TB60 is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA08TB60 is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY

V_R	600 V
V_F at 8 A at 25 °C	1.7 V
$I_{F(AV)}$	8 A
t_{rr} (typical)	18 ns
T_J (maximum)	150 °C
Q_{rr} (typical)	65 nC
$di_{(rec)M}/dt$ (typical)	240 A/μs
I_{RRM}	5.0 A

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		600	V
Maximum continuous forward current	I_F	$T_C = 100\text{ °C}$	8.0	A
Single pulse forward current	I_{FSM}		60	
Maximum repetitive forward current	I_{FRM}		24	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	36	W
		$T_C = 100\text{ °C}$	14	
Operating junction and storage temperature range	T_J, T_{Stg}		- 55 to + 150	°C

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 µA		600	-	- V
Maximum forward voltage	V _{FM}	I _F = 8.0 A	See fig. 1	-	1.4	1.7
		I _F = 16 A		-	1.7	2.1
		I _F = 8.0 A, T _J = 125 °C		-	1.4	1.7
Maximum reverse leakage current	I _{RM}	V _R = V _R rated	See fig. 2	-	0.3	5.0
		T _J = 125 °C, V _R = 0.8 x V _R rated		-	100	500 µA
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	10	25 pF
Series inductance	L _S	Measured lead to lead 5 mm from package body		-	8.0	- nH

DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Reverse recovery time	t _{rr}	I _F = 1.0 A, dI _F /dt = 200 A/µs, V _R = 30 V		-	18	-
	t _{rr1}	T _J = 25 °C	I _F = 8.0 A dI _F /dt = 200 A/µs V _R = 200 V	-	37	55
	t _{rr2}	T _J = 125 °C		-	55	90
Peak recovery current	I _{RRM1}	T _J = 25 °C		-	3.5	5.0
	I _{RRM2}	T _J = 125 °C		-	4.5	8.0
Reverse recovery charge	Q _{rr1}	T _J = 25 °C		-	65	138
	Q _{rr2}	T _J = 125 °C		-	124	360
Peak rate of fall of recovery current during t _b	dI _(rec) /dt1	T _J = 25 °C		-	240	-
	dI _(rec) /dt2	T _J = 125 °C		-	210	-

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s		-	-	300 °C
Thermal resistance, junction to case	R _{thJC}			-	-	3.5
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount		-	-	80
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased		-	0.5	-
Weight				-	2.0	- g
				-	0.07	- oz.
Mounting torque				6.0 (5.0)	-	12 (10) kgf · cm (lbf · in)
Marking device		Case style TO-220AC		HFA08TB60		

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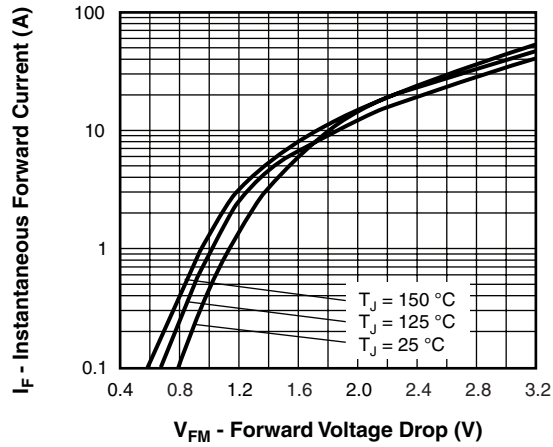


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

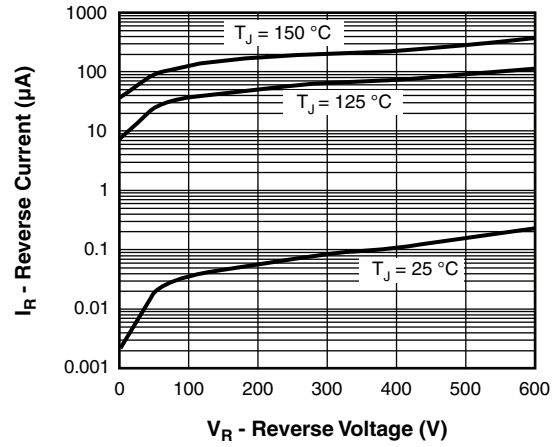


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

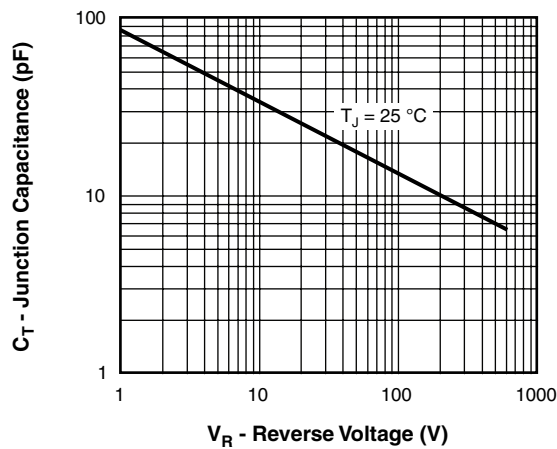


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

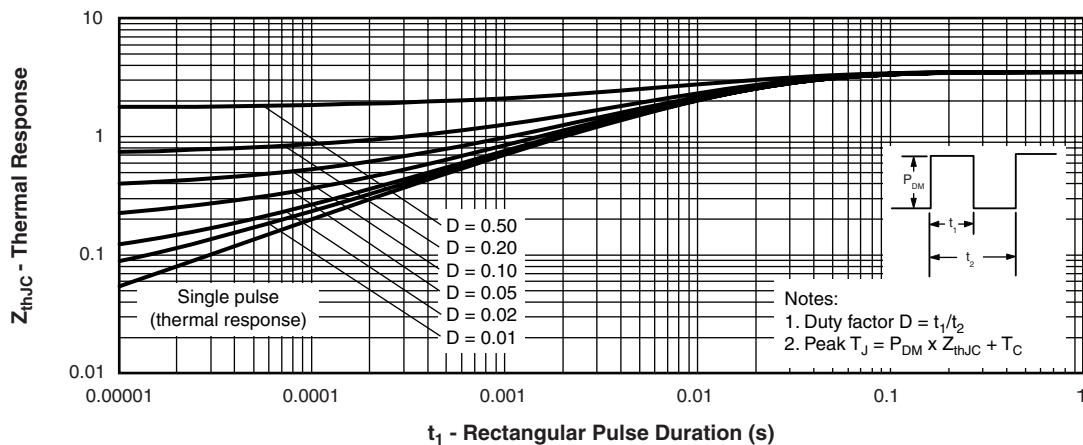
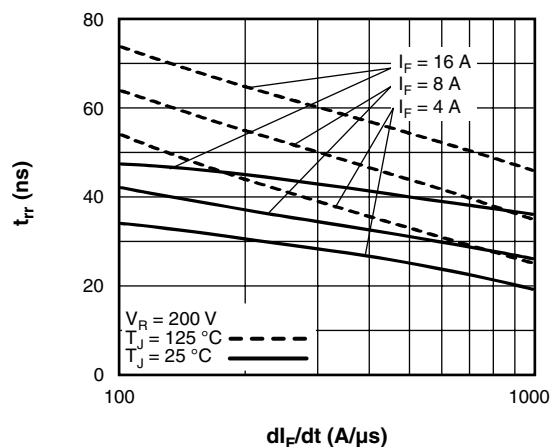
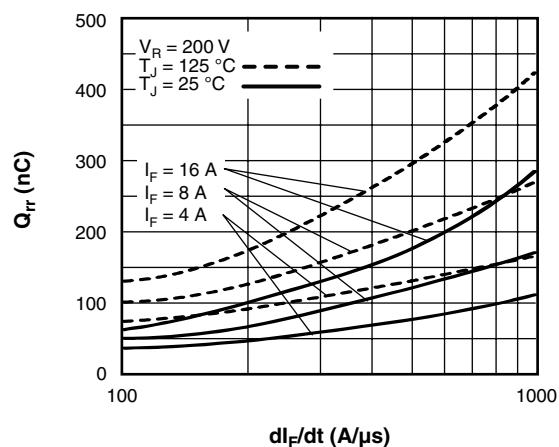
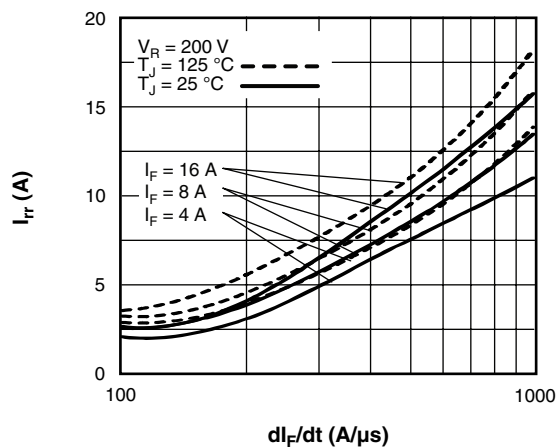
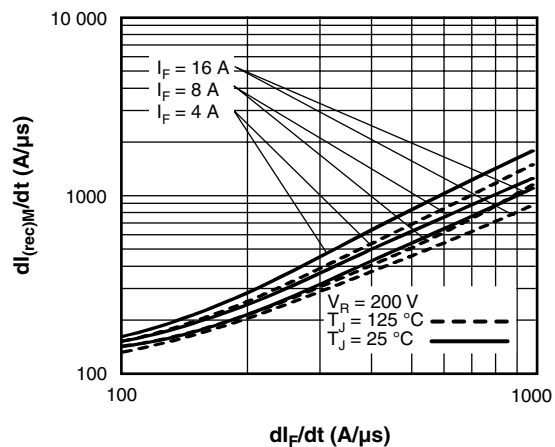


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt Fig. 7 - Typical Stored Charge vs. dI_F/dt Fig. 6 - Typical Recovery Current vs. dI_F/dt Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt

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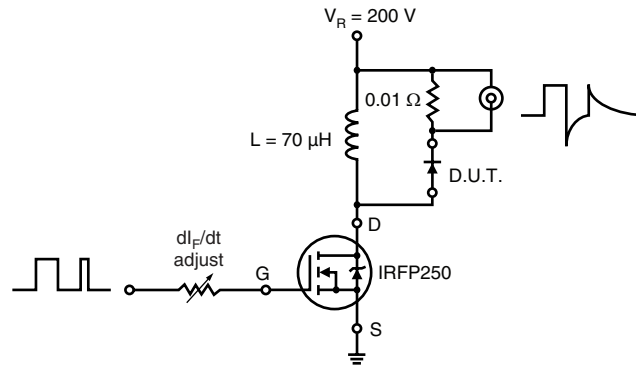


Fig. 9 - Reverse Recovery Parameter Test Circuit

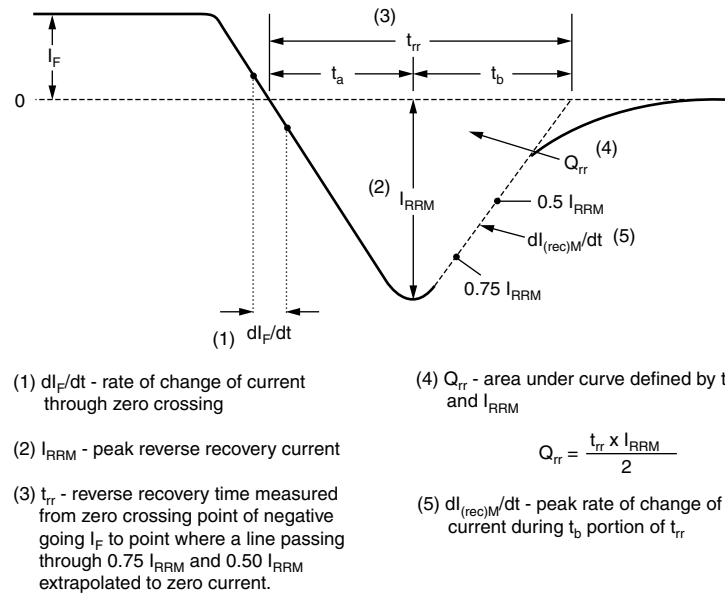


Fig. 10 - Reverse Recovery Waveform and Definitions

LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95221
Part marking information	http://www.vishay.com/doc?95224



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